

## T493C105K050AB6110

T493 HRA, Tantalum, MnO2 Tantalum, HRA, 1 uF, 10%, 50 VDC, SMD, MnO2, Molded, High Reliability, N/A, 5.5 Ohms, 6032, 2.8 mm, 1.3 mm

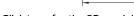
CATHODE (-) END VIEW



ANODE (+) END VIEW

ΗB **-**S ---- |- s-— G – BOTTOM VIEW Δ. pad shape/design at KEMET's option

SIDE VIEW



Click here	for the 3D	) model.
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General Information	
Series	T493 HRA
Dielectric	MnO2 Tantalum
Style	SMD Chip
Description	SMD, MnO2, Molded, High Reliability
Features	High Reliability
RoHS	Yes
Termination	Gold
AEC-Q200	No
Typical Component Weight	224.2 mg
Notes	P and R dimensions represents the minimum solderable area of the termination surface entirely below cutout (if one is present).

Dimensions		Specifications
L	6mm +/-0.3mm	Capacitance
W	3.2mm +/-0.3mm	Tolerance
Н	2.5mm +/-0.3mm	Voltage DC
т	0.13mm REF	Temperature Range
S	1.3mm +/-0.3mm	Rated Temperature
F	2.2mm +/-0.1mm	<b>Dissipation Factor</b>
A	3.1mm MIN	Failure Rate
В	0.5mm +/-0.15mm	ESR
E	2.4mm REF	<b>Ripple Current</b>
G	2.8mm REF	Leakage Current
Ρ	0.5mm MIN	Testing and Reliability
R	1mm REF	
Х	0.1mm +/-0.1mm REF	

Specifications	
Capacitance	1uF
Tolerance	10%
Voltage DC	50 VDC (85C), 33.5 VDC (125C)
Temperature Range	-55/+125°C
Rated Temperature	85°C
Dissipation Factor	4% 120Hz 25C
Failure Rate	N/A
ESR	5.5 Ohms (100kHz 25C)
Ripple Current	141 mA (rms, 100kHz 25C)
Leakage Current	0.5 uA (5min 25°C)

Standard Testing Only

Packaging Specifications		
Packaging	T&R, 178mm	
Packaging Quantity	500	

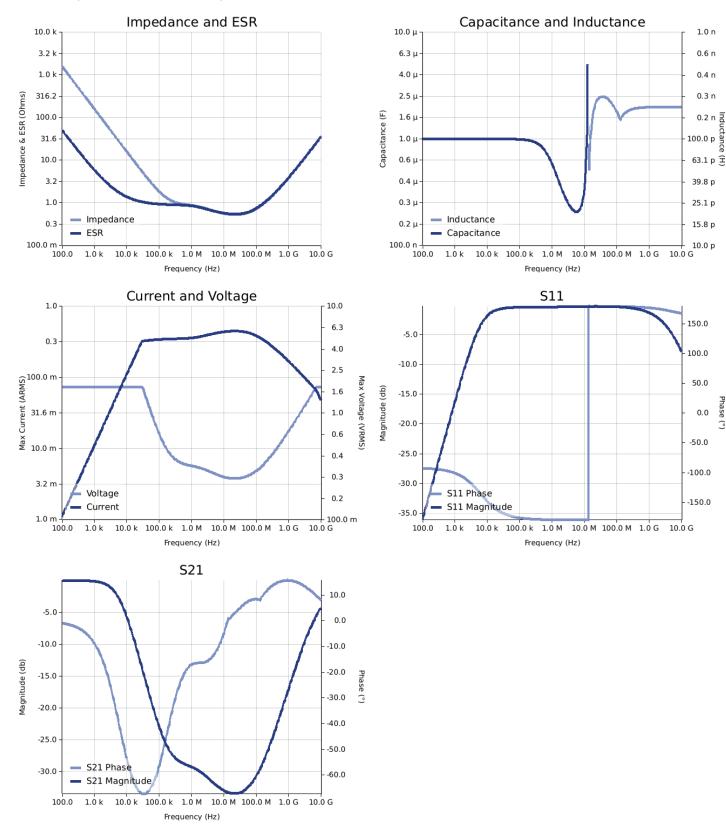
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MnO2, Molded, High Reliability, N/A, 5.5 Ohms, 6032, 2.8 mm, 1.3 mm

## Simulations

For the complete simulation environment please visit K-SIM.



tan

Phase (°)



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## These are simulations.

This is not a specification!

The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

The responses shown do not represent a specified or implied maximum capability of the device for all applications.

- The ESR used for ripple "Ripple Current/Voltage vs. Frequency" plots is the ESR at ambient temperature.

- The ESR used for hipple klipple current younge vs. requericy plots is the ESR at an bient temperature.
  The ESR in the "Temperature Rise vs. Ripple Current" plots is adjusted to each incremental temperature rise before the power and ripple current is calculated.
  The effects shown herein are based on measured data from a multiple part sample of the parts in question.
  Ripple capability of this device will be factored by thermal resistance (Rth) created by circuit traces (addi affects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.
  The peak voltages generated in the "Temperature Rise vs. Combined Ripple Currents" plot are calculated for each frequency and are not combined with voltages and the part of the parts of the part of the
- generated at any other harmonics.
  Please consult with the catalog or field applications engineer for maximum capability of the device in specific applications.

All product information and data (collectively, the "Information") are subject to change without notice.

KEMET K-SIM is designed to simulate behavior of components with respect to frequency, ambient temperature, and DC bias levels. The responses shown represent the typical response for each part type. Specific responses may vary, depending on manufacturing variation effects of all parameters involved, including the specified tolerances applied to capacitance and unspecified variations of ESR, ESL, and leakage resistance.

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If you have any questions please contact K-SIM.